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# FDMS4D4N08C

## N-Channel Shielded Gate PowerTrench® MOSFET 80 V, 123 A, 4.3 mΩ

### Features

- Shielded Gate MOSFET Technology
- Max  $r_{DS(on)}$  = 4.3 mΩ at  $V_{GS} = 10$  V,  $I_D = 44$  A
- Max  $r_{DS(on)}$  = 10.4 mΩ at  $V_{GS} = 6$  V,  $I_D = 22$  A
- 50% Lower Qrr than Other MOSFET Suppliers
- Lowers Switching Noise/EMI
- MSL1 Robust Package Design
- 100% UIL Tested
- RoHS Compliant

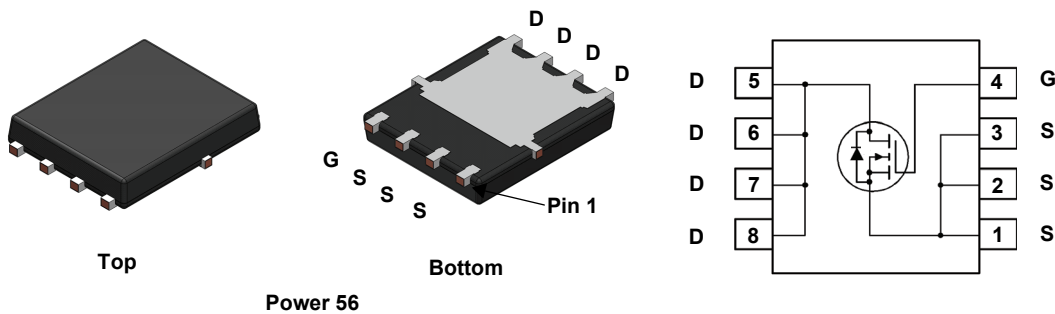


### General Description

This N-Channel MV MOSFET is produced using ON Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized to minimise on-state resistance and yet maintain superior switching performance with best in class soft body diode.

### Applications

- Primary DC-DC MOSFET
- Synchronous Rectifier in DC-DC and AC-DC
- Motor Drive
- Solar



Power 56

### MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Rated	Units
$V_{DS}$	Drain to Source Voltage	80	V
$V_{GS}$	Gate to Source Voltage	±20	V
$I_D$	Drain Current -Continuous	$T_C = 25$ °C (Note 5)	123
	-Continuous	$T_C = 100$ °C (Note 5)	78
	-Continuous	$T_A = 25$ °C (Note 1a)	17
	-Pulsed	(Note 4)	498
$E_{AS}$	Single Pulse Avalanche Energy	(Note 3)	486
$P_D$	Power Dissipation	$T_C = 25$ °C	125
	Power Dissipation	$T_A = 25$ °C (Note 1a)	2.5
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	°C

### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS4D4N08C	FDMS4D4N08C	Power 56	13 "	12 mm	3000 units

## Electrical Characteristics $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250\text{ }\mu\text{A}$ , $V_{GS} = 0\text{ V}$	80			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , referenced to $25\text{ }^\circ\text{C}$		63		mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 64\text{ V}$ , $V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{ V}$ , $V_{DS} = 0\text{ V}$			$\pm 100$	nA

### On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250\text{ }\mu\text{A}$	2.0	3.0	4.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , referenced to $25\text{ }^\circ\text{C}$		-8.2		mV/ $^\circ\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}$ , $I_D = 44\text{ A}$		3.7	4.3	m $\Omega$
		$V_{GS} = 6\text{ V}$ , $I_D = 22\text{ A}$		5.7	10.4	
		$V_{GS} = 10\text{ V}$ , $I_D = 44\text{ A}$ , $T_J = 125\text{ }^\circ\text{C}$		5.9	7.2	
$g_{FS}$	Forward Transconductance	$V_{DS} = 5\text{ V}$ , $I_D = 44\text{ A}$		98		S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 40\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1\text{ MHz}$		2920	4090	pF
$C_{oss}$	Output Capacitance			1045	1465	pF
$C_{rss}$	Reverse Transfer Capacitance			35	50	pF
$R_g$	Gate Resistance		0.1	1.3	2.5	$\Omega$

### Switching Characteristics

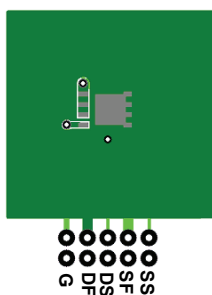
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 40\text{ V}$ , $I_D = 44\text{ A}$ , $V_{GS} = 10\text{ V}$ , $R_{GEN} = 6\text{ }\Omega$		17	31	ns
$t_r$	Rise Time			7	15	ns
$t_{d(off)}$	Turn-Off Delay Time			25	40	ns
$t_f$	Fall Time			5	10	ns
$Q_g$	Total Gate Charge		$V_{GS} = 0\text{ V to }10\text{ V}$	40	56	nC
$Q_g$	Total Gate Charge	$V_{GS} = 0\text{ V to }6\text{ V}$	25	35	nC	
$Q_{gs}$	Gate to Source Charge	$V_{DD} = 40\text{ V}$ , $I_D = 44\text{ A}$		13		nC
$Q_{gd}$	Gate to Drain "Miller" Charge			8		nC
$Q_{oss}$	Output Charge		$V_{DD} = 40\text{ V}$ , $V_{GS} = 0\text{ V}$		60	
$Q_{sync}$	Total Gate Charge Sync.	$V_{DS} = 0\text{ V}$ , $I_D = 44\text{ A}$		35		nC

### Drain-Source Diode Characteristics

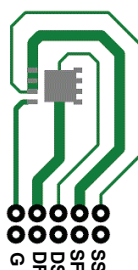
$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{ V}$ , $I_S = 2.1\text{ A}$ (Note 2)		0.7	1.2	V
		$V_{GS} = 0\text{ V}$ , $I_S = 44\text{ A}$ (Note 2)		0.8	1.3	
$t_{rr}$	Reverse Recovery Time	$I_F = 22\text{ A}$ , $di/dt = 300\text{ A}/\mu\text{s}$		26	42	ns
$Q_{rr}$	Reverse Recovery Charge			44	71	nC
$t_{rr}$	Reverse Recovery Time	$I_F = 22\text{ A}$ , $di/dt = 1000\text{ A}/\mu\text{s}$		20	32	ns
$Q_{rr}$	Reverse Recovery Charge			106	169	nC

#### Notes:

1.  $R_{\theta JA}$  is determined with the device mounted on a  $1\text{ in}^2$  pad 2 oz copper pad on a  $1.5 \times 1.5\text{ in.}$  board of FR-4 material.  $R_{\theta CA}$  is determined by the user's board design.



$50\text{ }^\circ\text{C/W}$  when mounted on a  $1\text{ in}^2$  pad of 2 oz copper



$125\text{ }^\circ\text{C/W}$  when mounted on a minimum pad of 2 oz copper.

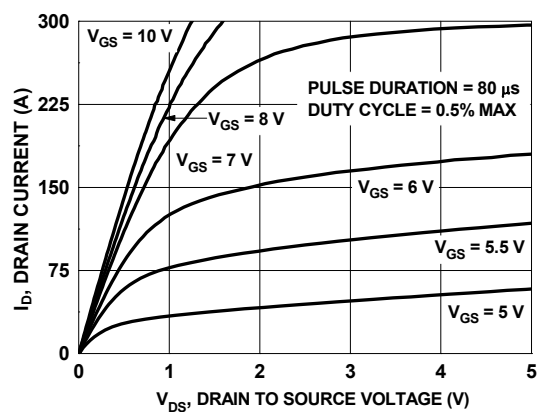
2. Pulse Test: Pulse Width <  $300\text{ }\mu\text{s}$ , Duty cycle < 2.0%.

3.  $E_{AS}$  of 486 mJ is based on starting  $T_J = 25\text{ }^\circ\text{C}$ ; N-ch:  $L = 3\text{ mH}$ ,  $I_{AS} = 18\text{ A}$ ,  $V_{DD} = 80\text{ V}$ ,  $V_{GS} = 10\text{ V}$ . 100% test at  $L = 0.1\text{ mH}$ ,  $I_{AS} = 51\text{ A}$ .

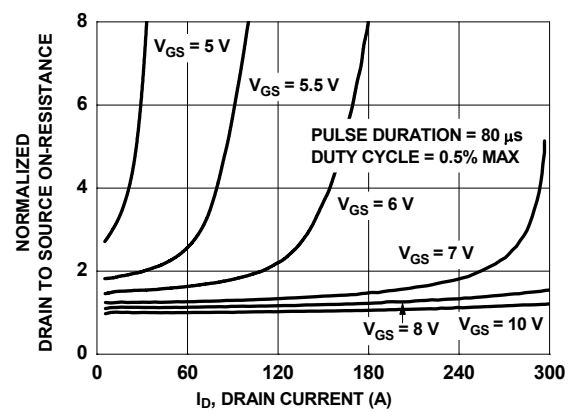
4. Pulsed  $I_d$  please refer to Fig 11 SOA graph for more details.

5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

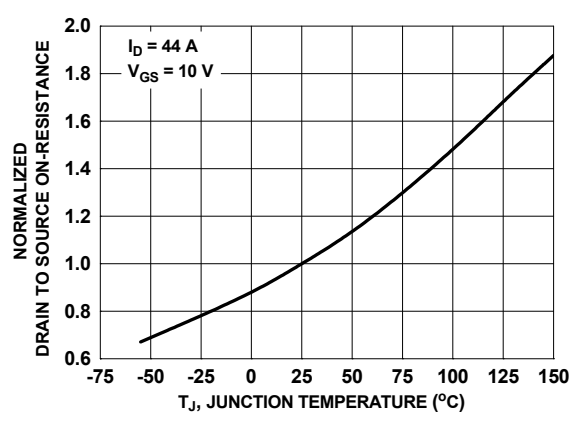
**Typical Characteristics**  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise noted.



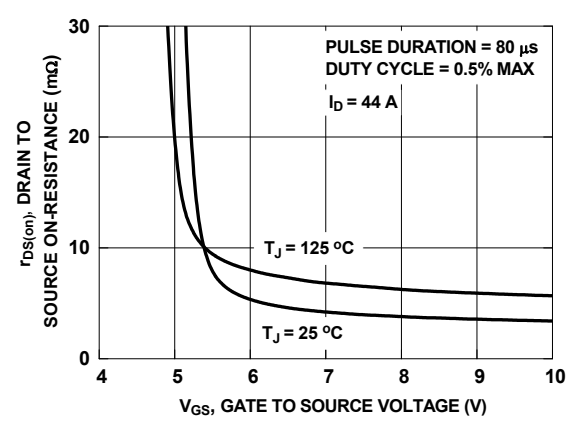
**Figure 1. On Region Characteristics**



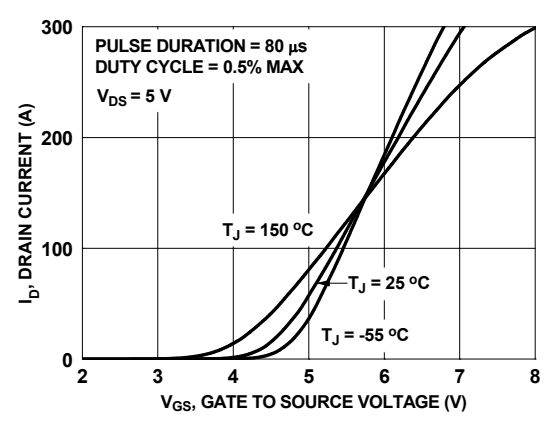
**Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage**



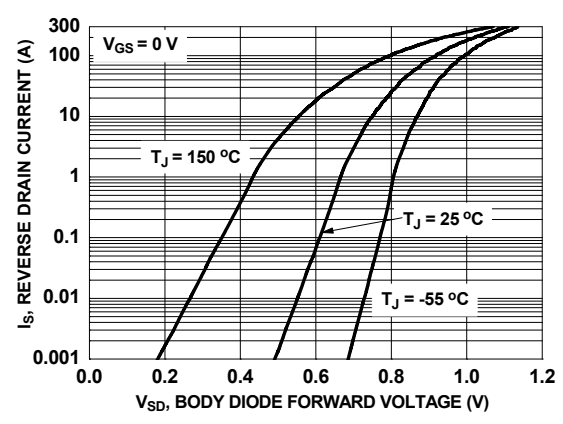
**Figure 3. Normalized On Resistance vs. Junction Temperature**



**Figure 4. On-Resistance vs. Gate to Source Voltage**

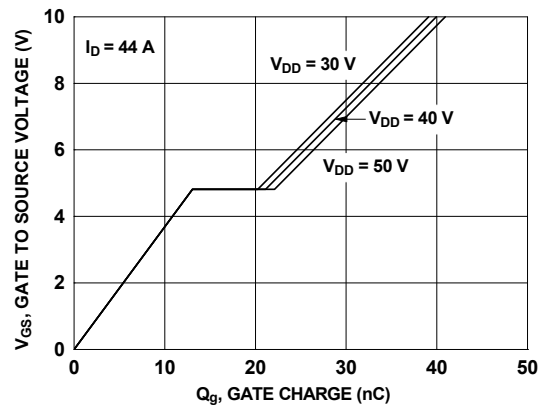


**Figure 5. Transfer Characteristics**

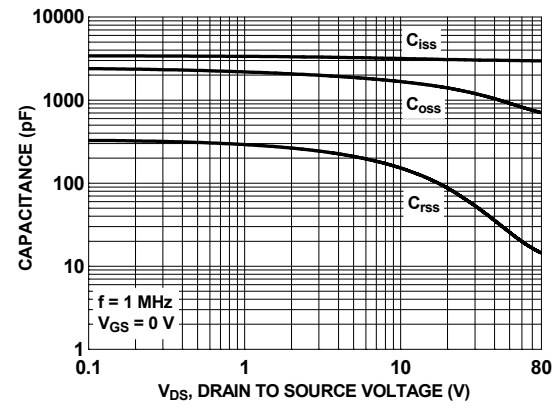


**Figure 6. Source to Drain Diode Forward Voltage vs. Source Current**

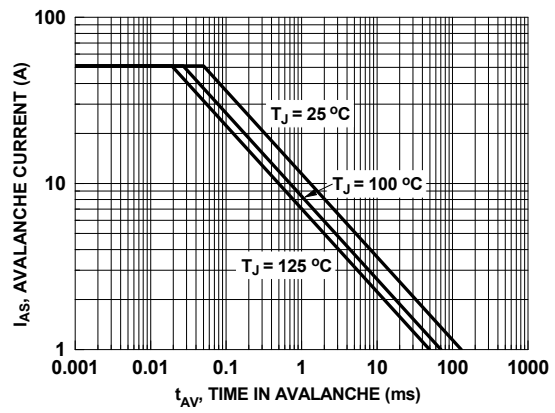
**Typical Characteristics**  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise noted.



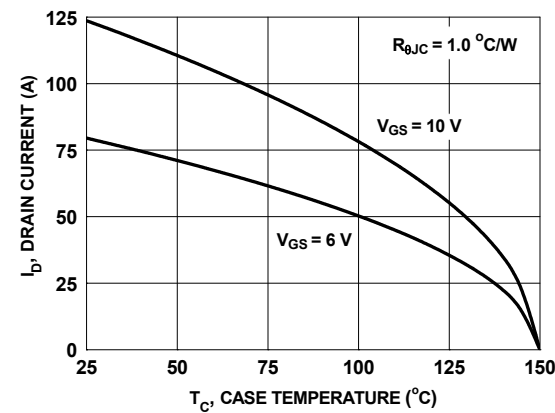
**Figure 7. Gate Charge Characteristics**



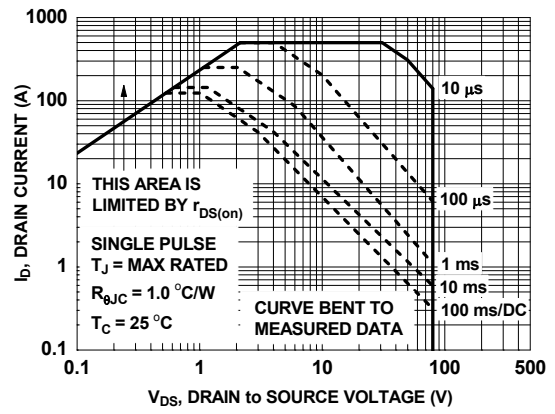
**Figure 8. Capacitance vs. Drain to Source Voltage**



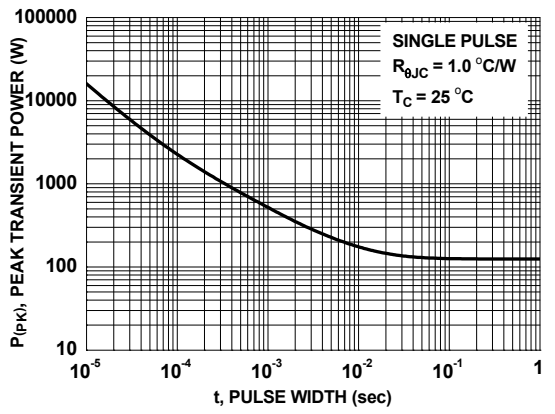
**Figure 9. Unclamped Inductive Switching Capability**



**Figure 10. Maximum Continuous Drain Current vs Case Temperature**

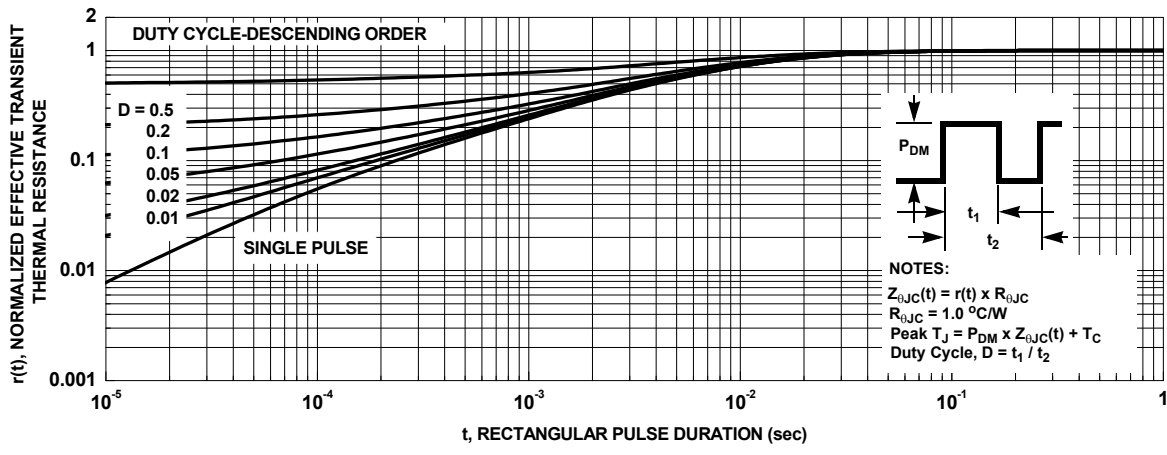


**Figure 11. Forward Bias Safe Operating Area**



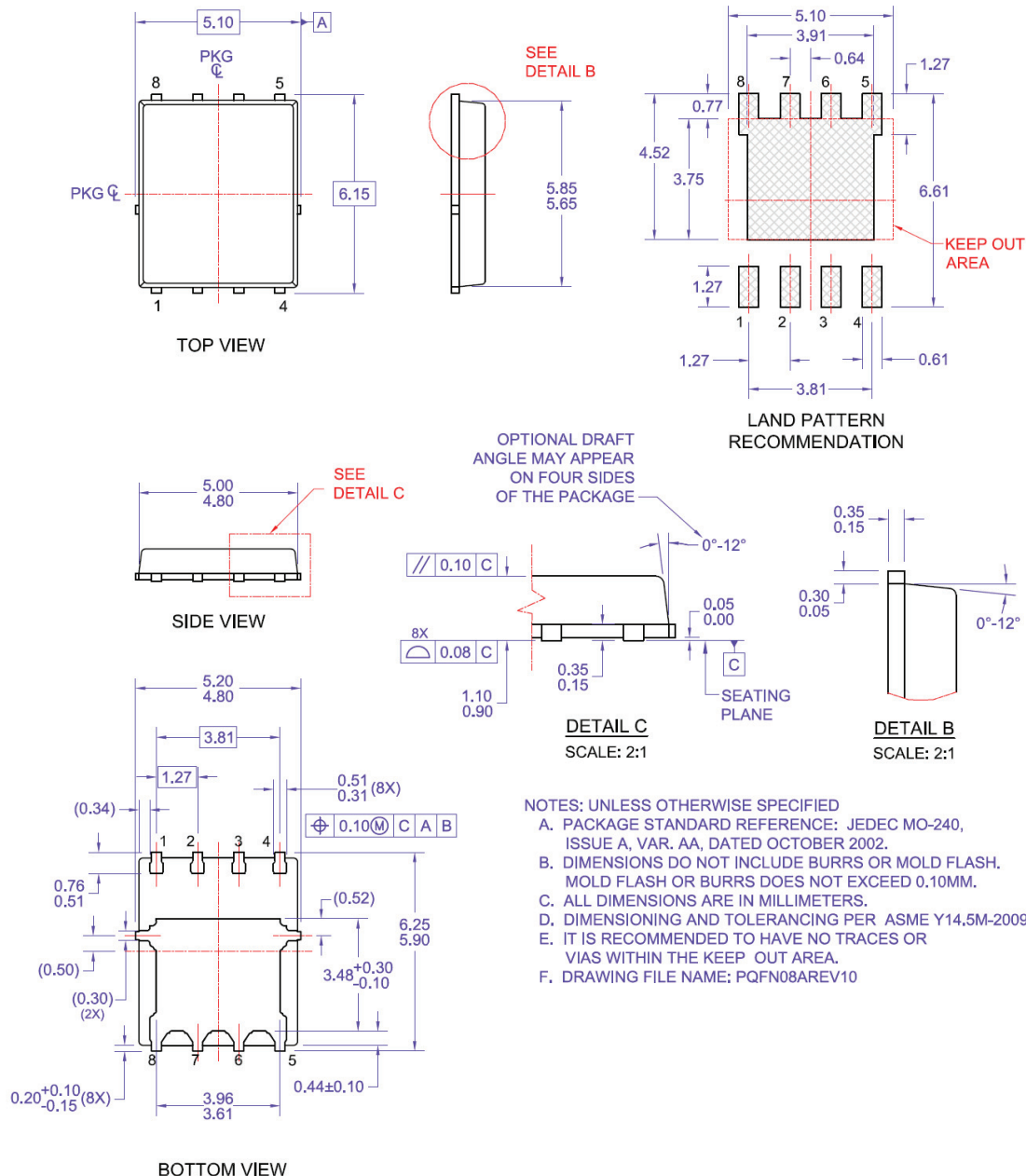
**Figure 12. Single Pulse Maximum Power Dissipation**

**Typical Characteristics**  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise noted.



**Figure 13. Junction-to-Case Transient Thermal Response Curve**

## Dimensional Outline and Pad Layout

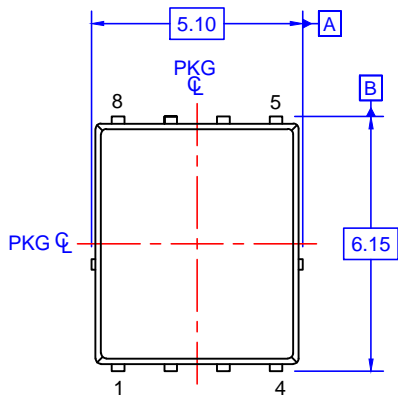


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  - DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
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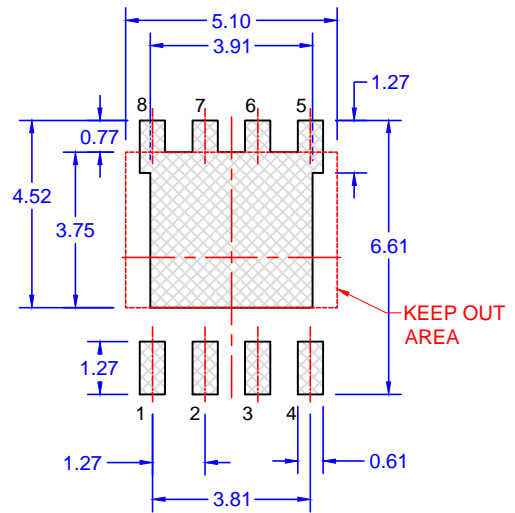
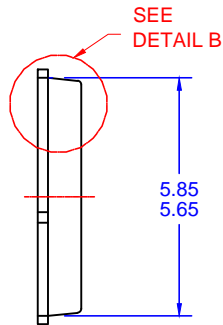
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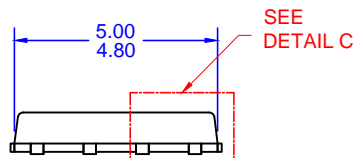
PQFN8 5X6, 1.27P  
CASE 483AE  
ISSUE A



TOP VIEW

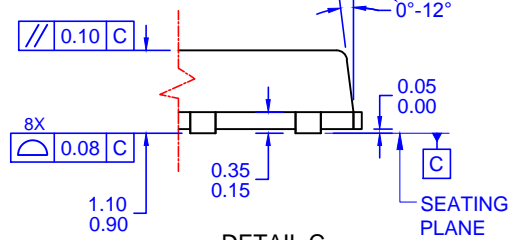


LAND PATTERN RECOMMENDATION

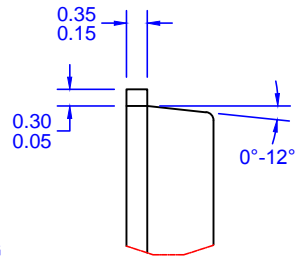


SIDE VIEW

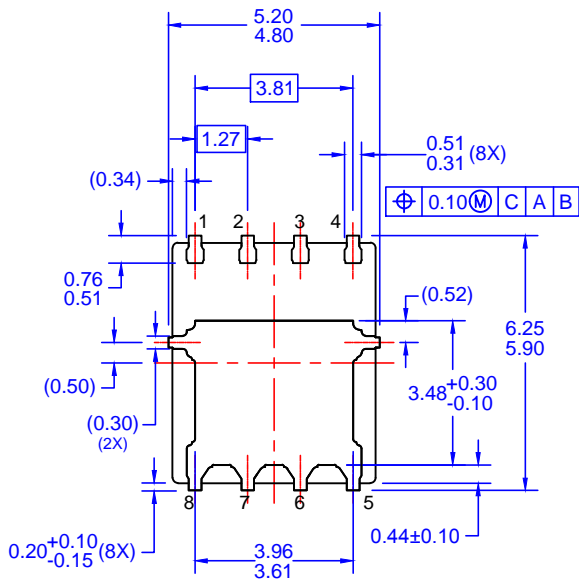
OPTIONAL DRAFT ANGLE MAY APPEAR ON FOUR SIDES OF THE PACKAGE



DETAIL C  
SCALE: 2:1



DETAIL B  
SCALE: 2:1



BOTTOM VIEW

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